ABSTRACT OF THE DISCLOSURE

BONDING WIRE FOR HIGH-SPEED SIGNAL LINE

An object is to provide a bonding wire for a high-speed signal line, formed by an Ag-Pd-Pt three-element alloy or an Ag-Pd-Pt ternary alloy, that is able to transmit a stable super-high frequency signal in a several GHz band, and that does not have a strong silver sulfide (Ag_2S) film even when an unstable silver sulfide layer is formed on the surface of the bonding wire. Provided is the bonding wire for the high-speed signal line formed by a three-element alloy containing 0.8 to 2.5 mass% of palladium (Pd), 0.1 to 0.7 mass% of platinum (Pt), and a balance being silver (Ag) with purity of 99.99 mass% or more, or a ternary alloy obtained by adding a trace element to the three-element alloy, in which cross section of the bonding wire is formed by a skin film and a core, and in which a surface segregation layer containing highly-concentrated silver (Ag) is present in the skin film of the silver alloy.

Figure 1